

DECLARATION

I, Aya FUKUDA, of KOKUBUN International Patents & Trademarks of Ikebukuro TG Homest Building, 17-8, Higashi-Ikebukuro 1-chome, Toshima-ku, Tokyo 170-0013 JAPAN, hereby declare that I am well acquainted with both the Japanese and English languages, that I made an English translation attached hereto, and that to the best of my knowledge and belief the translation is a true and correct reproduction of the original documents filed with the U.S. Patent and Trademark Office in respect of U.S. Patent Application No. 09/350,125 on July 9, 1999.

Signed this 17th day of September, 1999

Aya Fukuda

Aya FUKUDA

DECLARATION AND POWER OF ATTORNEY

U.S.A.

As a below-named inventor, I hereby declare: My residence, post office address and citizenship are as stated below next to my name. I believe I am the original, first, and sole inventor (if only one name is listed below) or an original, first, and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SPHERICAL SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME, the specification of which

☐ is attached hereto.

☒ was filed on July 9, 1999 application Serial No. 09/350,125 and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above, and acknowledge a duty to disclose information which is material to the examination of this application under 37 CFR 1.56(a). I hereby claim priority benefits under 35 U.S.C. §119 based on any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate on the present invention, filed before the application(s) in which priority is claimed.

FOREIGN APPLICATION(S), IF ANY, REFERRED TO ABOVE			
COUNTRY	APPLICATION NO.	DATE	PRIORITY CLAIMED
JAPAN	10-210442	July 9, 1998	YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>
JAPAN	10-210443	July 9, 1998	YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>

I hereby claim benefit under 35 U.S.C. §120 of any U.S. application(s) listed below. If the subject matter of any claim(s) of this application is not disclosed in the prior U.S. application(s) as required by paragraph one of 35 U.S.C. §112, I acknowledge a duty to disclose material information as defined in 37 CFR 1.56(a) regarding occurrences between the filing date of the prior application(s) and the national or PCT international filing date of this application.

SERIAL NUMBER	FILING DATE	STATUS

I hereby appoint Elliott I. Pollock, RN (Registration No.) 16,906; George Vande Sande, RN 17,276; Robert R. Priddy, RN 20,169; Burton A. Amernick, RN 24,852; Stanley B. Green, RN 24,351; Richard Wiener, RN 18,741; Townsend M. Belser, Jr., RN 22,956; Morris Liss, RN 24,510; Martin Abramson, RN 25,787; George R. Pettit, RN 27,369; Louis Woo, RN 31,730; Elzbieta Chlopecka, RN 32,767; and Eric Franklin, RN 37,134, my attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Address all communications to Pollock, Vande Sande & Priddy, P.O. Box 19088, Washington, D. C. 20036-3425.

All statements made herein of my own knowledge are true. All statements made on information and belief are believed to be true. These statements were made with the knowledge that willful false statements and the like so made are punishable by fine, imprisonment, or both, under 18 U.S.C. 1001 and may jeopardize the validity of the application or any patent issuing thereon.

Note: Please sign one full given name and your surname, using initials where appropriate for other names. It is important that the name be consistent throughout the application papers. Signing of an application more than five weeks prior to filing or an undated application is not acceptable to the Patent and Trademark Office except for receiving an initial filing date.

- Full name of inventor Kohei Tatum. Date: August 9, 1999
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11. Full name of inventor

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